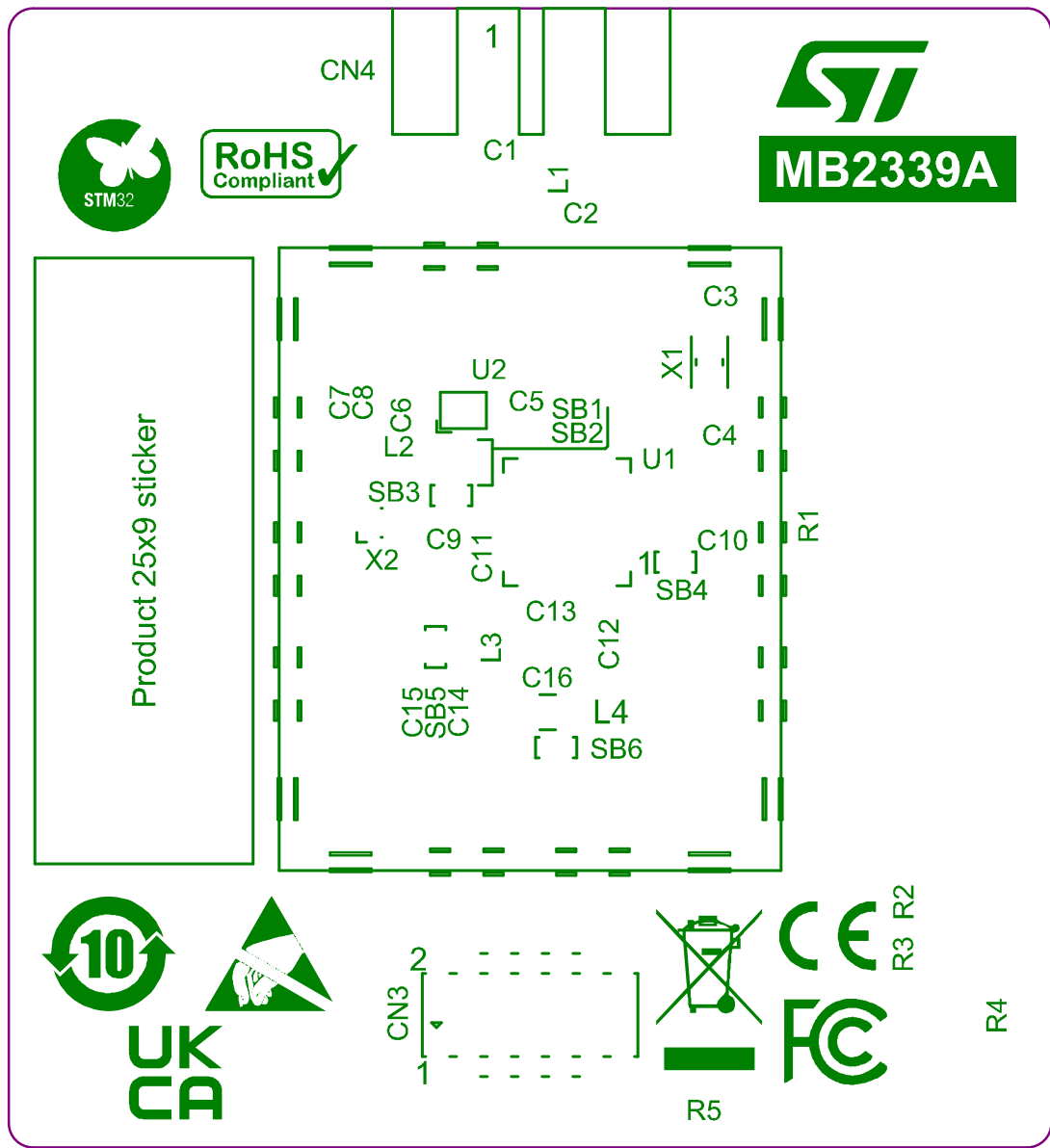




Project: MCU_RF_WL3R_QFN32

Layer: **Top Overlay**

Gerber: **.GTO**

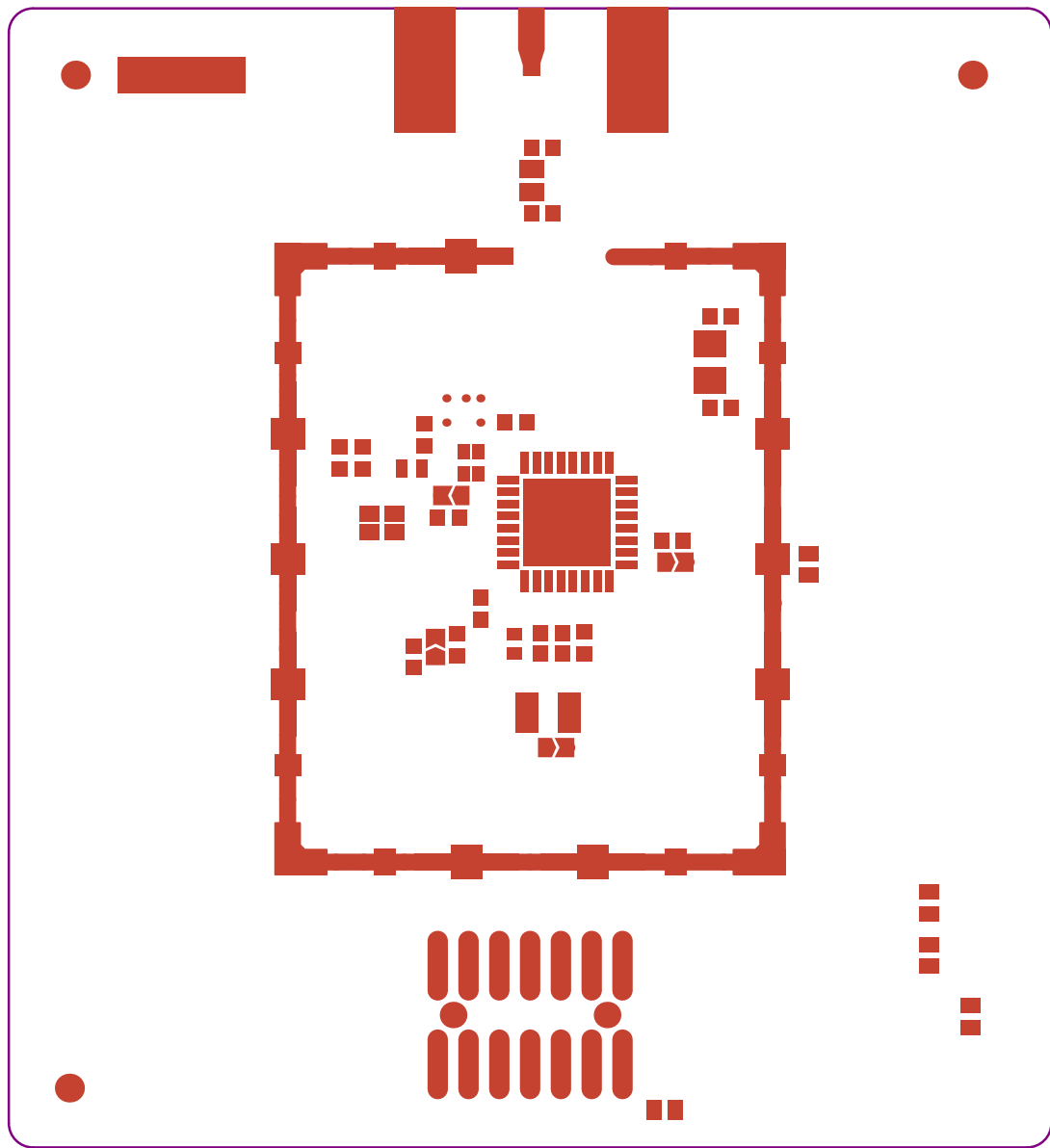
Variant: [No Variations]

Ref: MB2339

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Project: MCU_RF_WL3R_QFN32

Layer: **Top Solder**

Gerber: **.GTS**

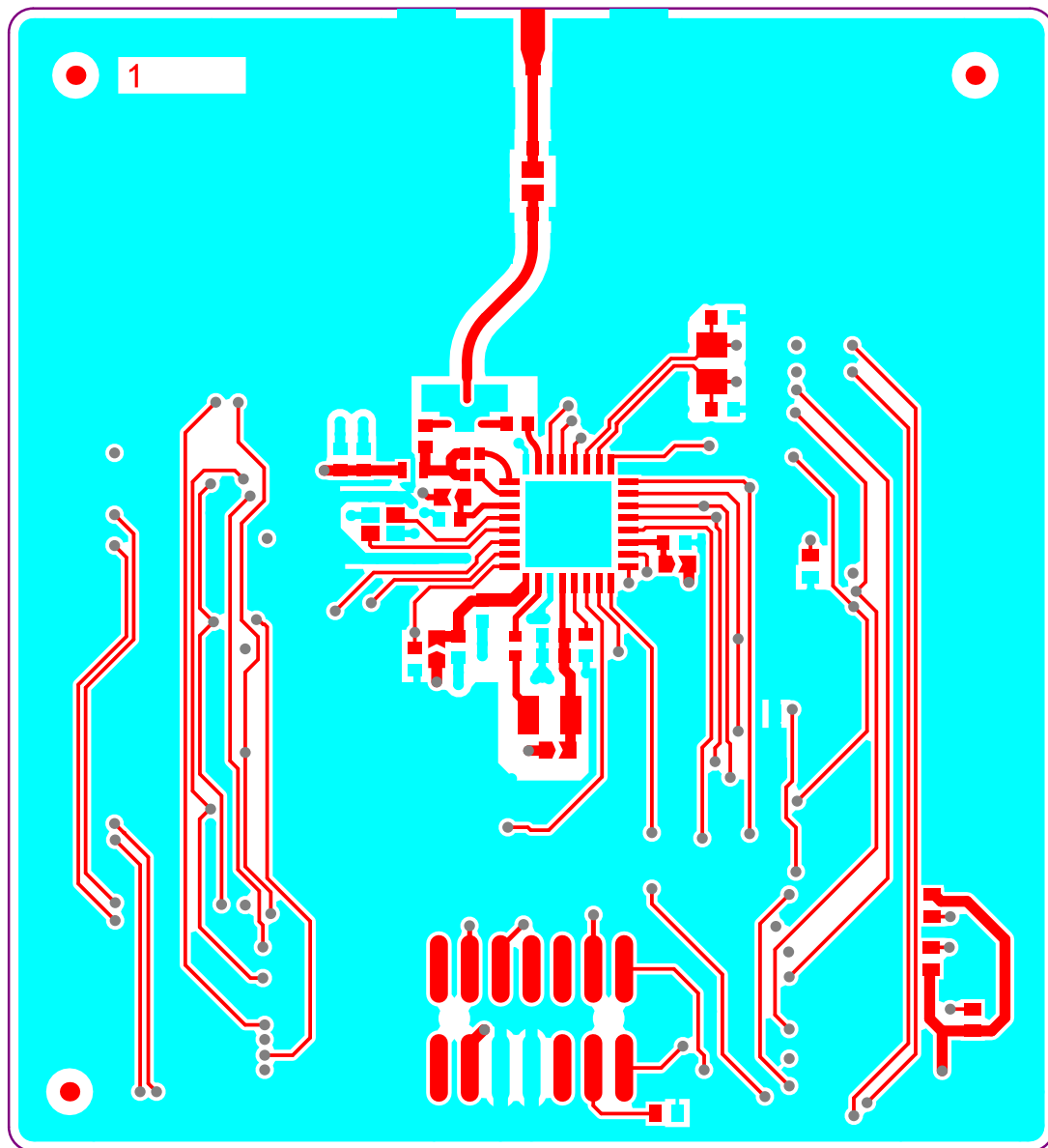
Variant: [No Variations]

Ref: MB2339

Date: 2025-MAR-06

Rev: A





Project: MCU_RF_WL3R_QFN32

Layer: **Top Layer**

Gerber: **.GTL**

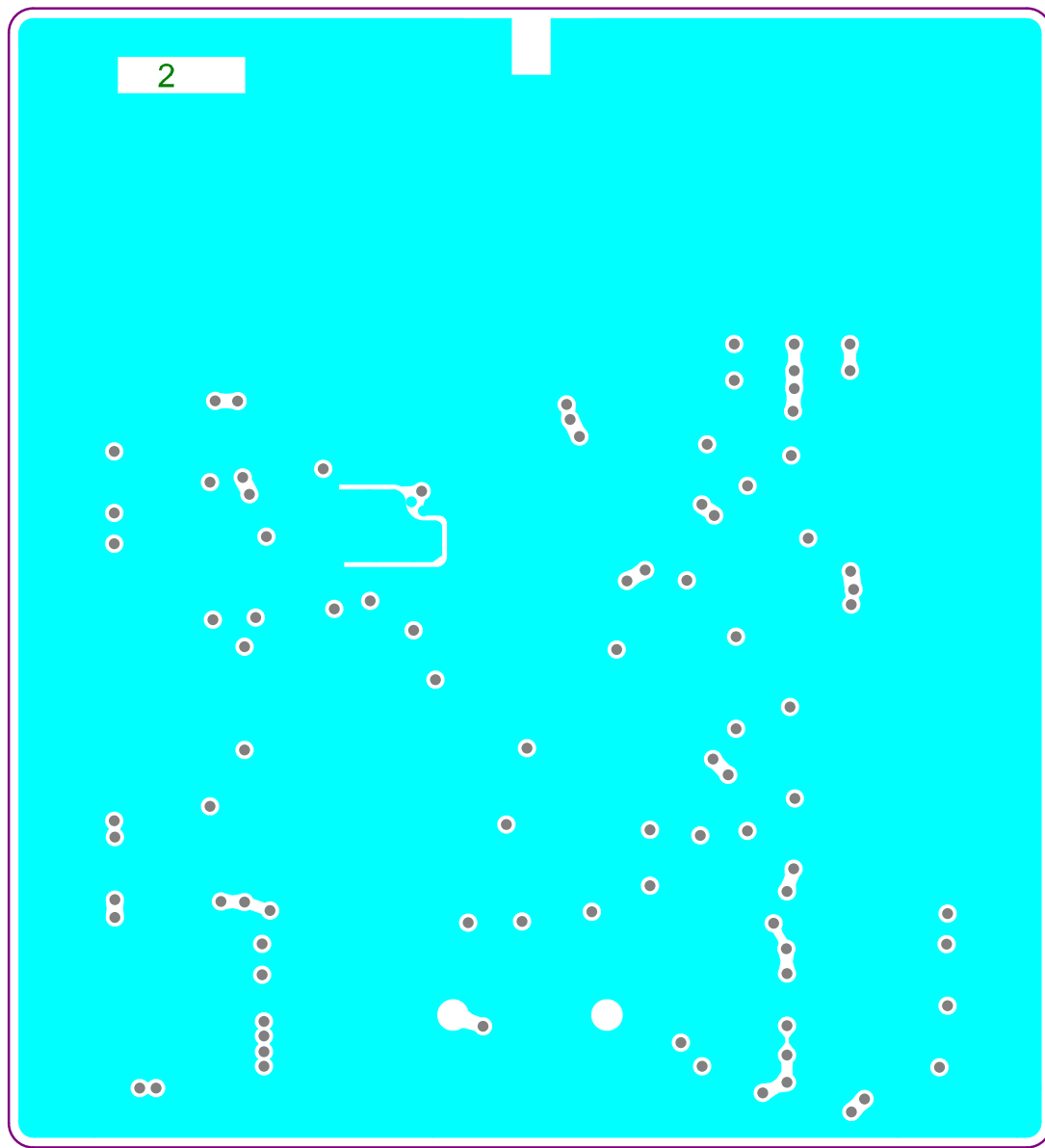
Variant: [No Variations]

Ref: MB2339

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Project: MCU_RF_WL3R_QFN32

Layer: Signal Layer 1

Gerber: .G1

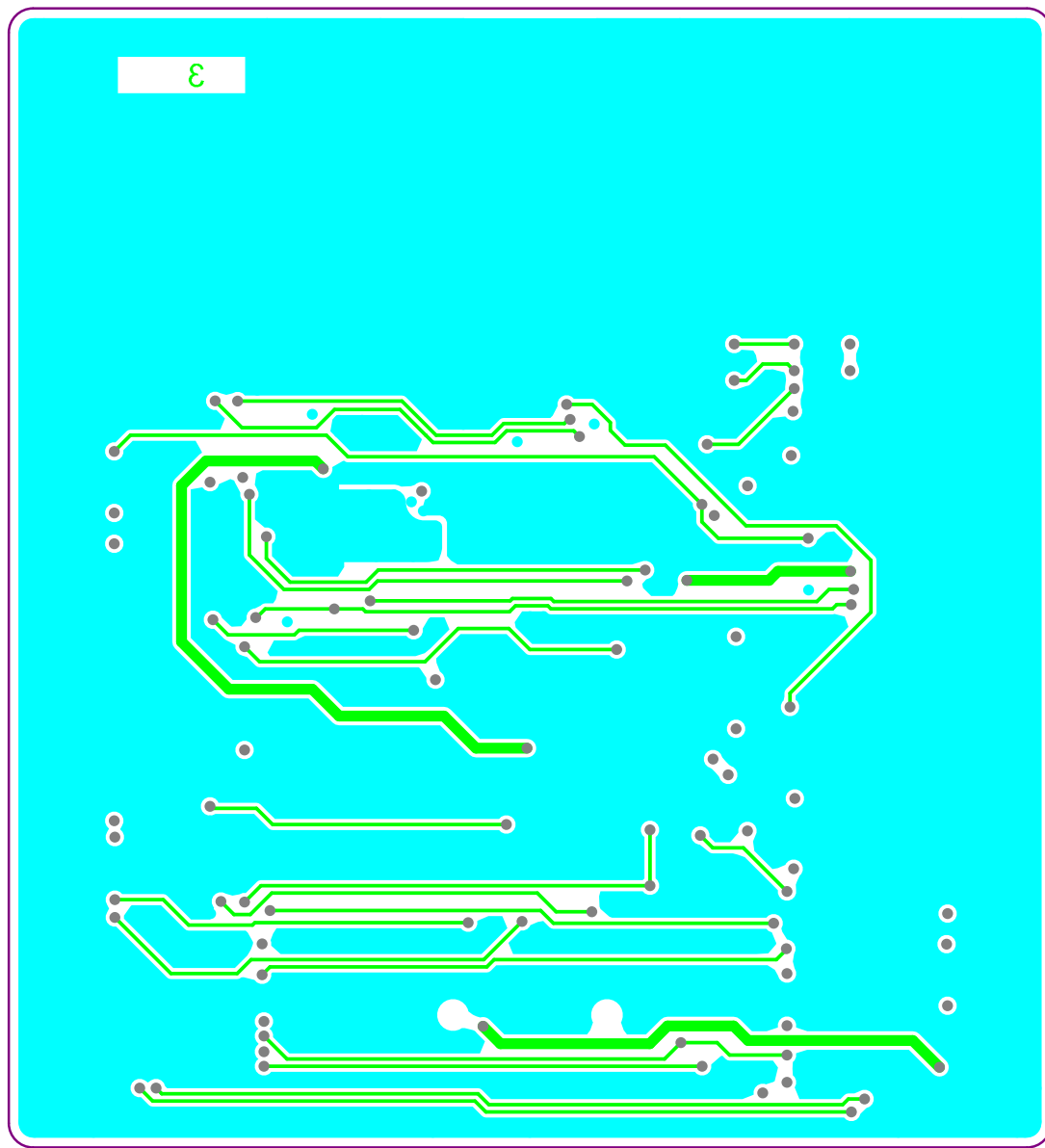
Variant: [No Variations]

Ref: MB2339

Date: 2025-MAR-06

Rev: A





Project: MCU_RF_WL3R_QFN32

Layer: Signal Layer 2

Gerber: .G2

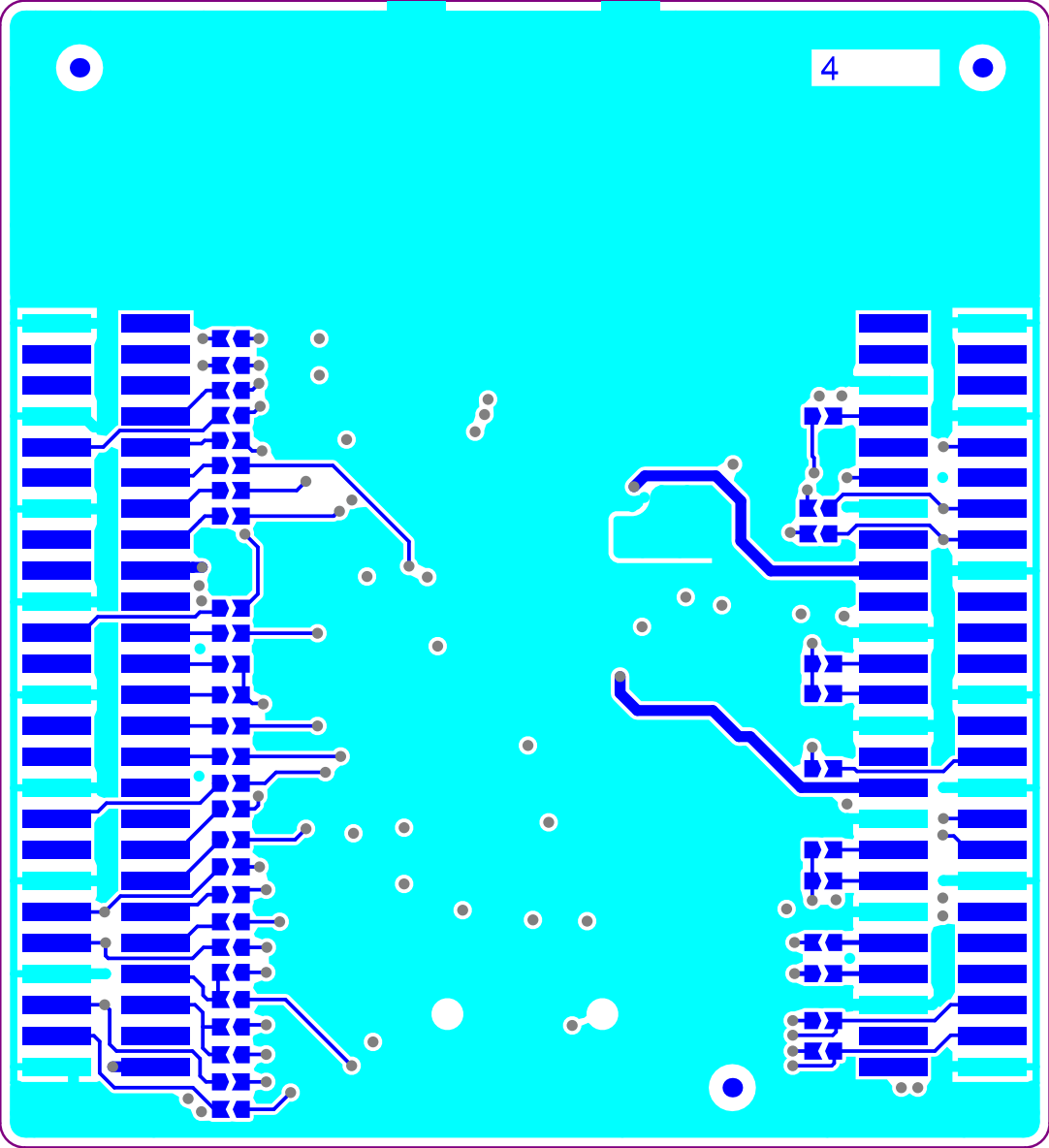
Variant: [No Variations]

Ref: MB2339

Date: 2025-MAR-06

Rev: A





Project: MCU_RF_WL3R_QFN32

Layer: Bottom Layer

Gerber:.GBL

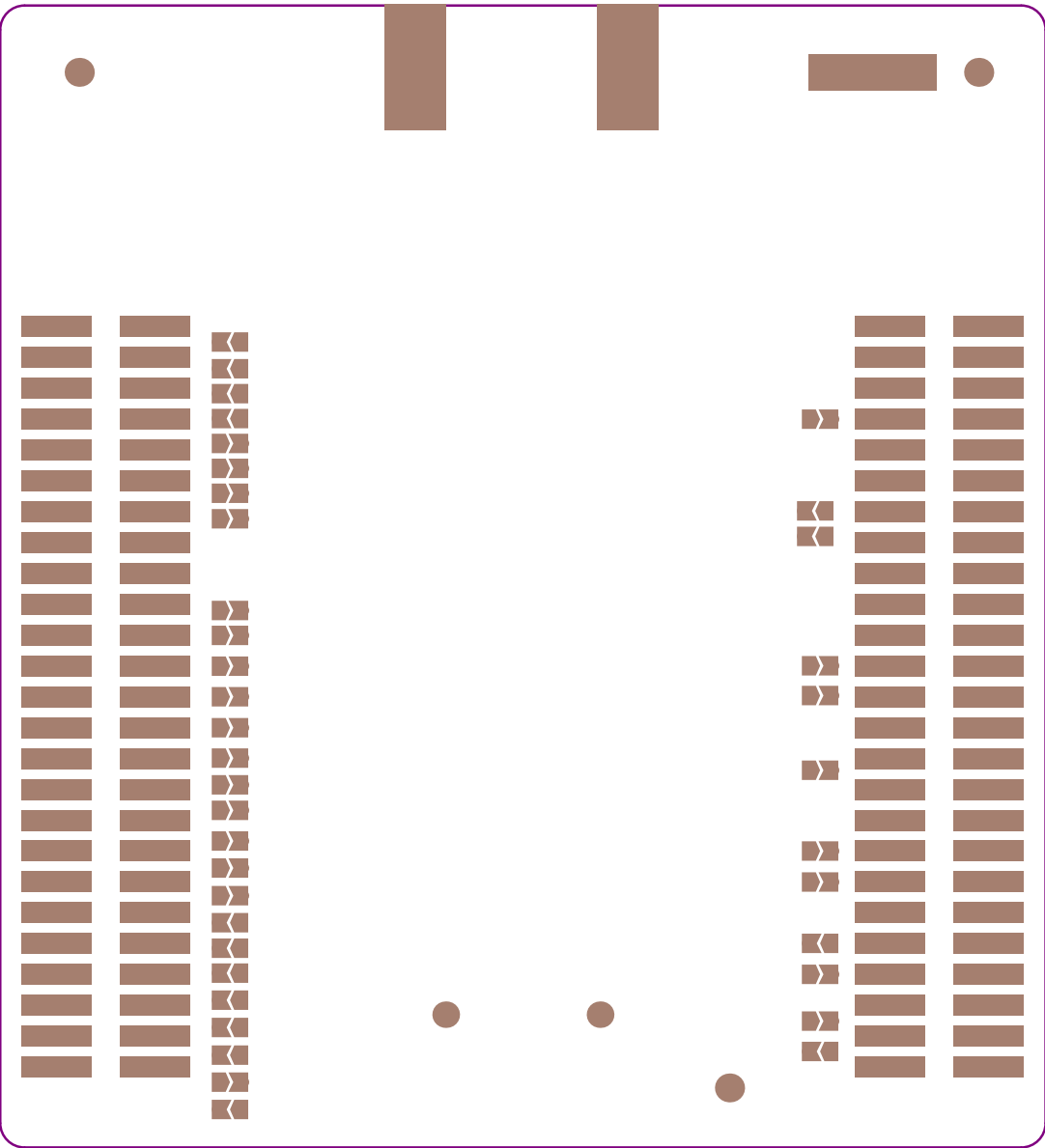
Variant: [No Variations]

Ref: MB2339

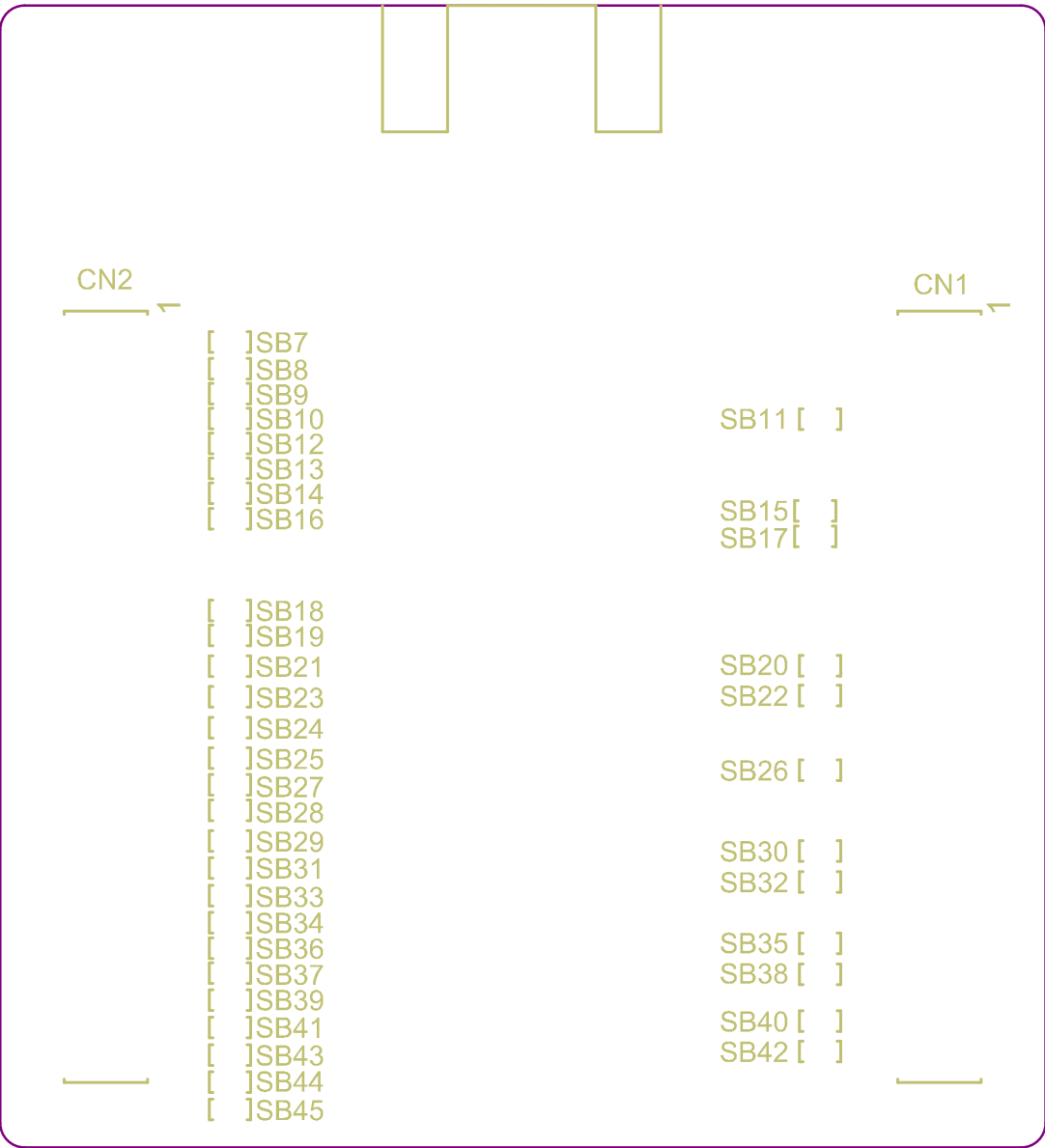
Date: 2025-MAR-06

Rev: A





Project: MCU_RF_WL3R_QFN32		
Layer: Bottom Solder	Gerber:.GBS	
Variant: [No Variations]	Ref: MB2339	
Date: 2025-MAR-06	Rev: A	



Project: MCU_RF_WL3R_QFN32		
Layer: Bottom Overlay	Gerber: .GBO	
Variant: [No Variations]	Ref: MB2339	
Date: 2025-MAR-06	Rev: A	

PCB SPECIFICATIONS :

A. MATERIAL :

FR-4

☐ TG-170

☒ TG-150

☐ TG-140

B. MATERIAL FAMILY :

N/A

C. SOLDERMASK COLOR :

☐ GREEN

☒ BLUE

☐ RED

☐ BLACK

D. SILKSCREEN COLOR :

☒ WHITE

☐ YELLOW

☐ BLACK

E. SURFACE FINISH :

☒ ENIG

☐ IMMERSION SILVER

☐ IMMERSION TIN

☐ HASL

☐ HASL (PB-FREE)

☐ GOLDEN FINGER

F. IMPEDANCE CONTROL :

☐ NO

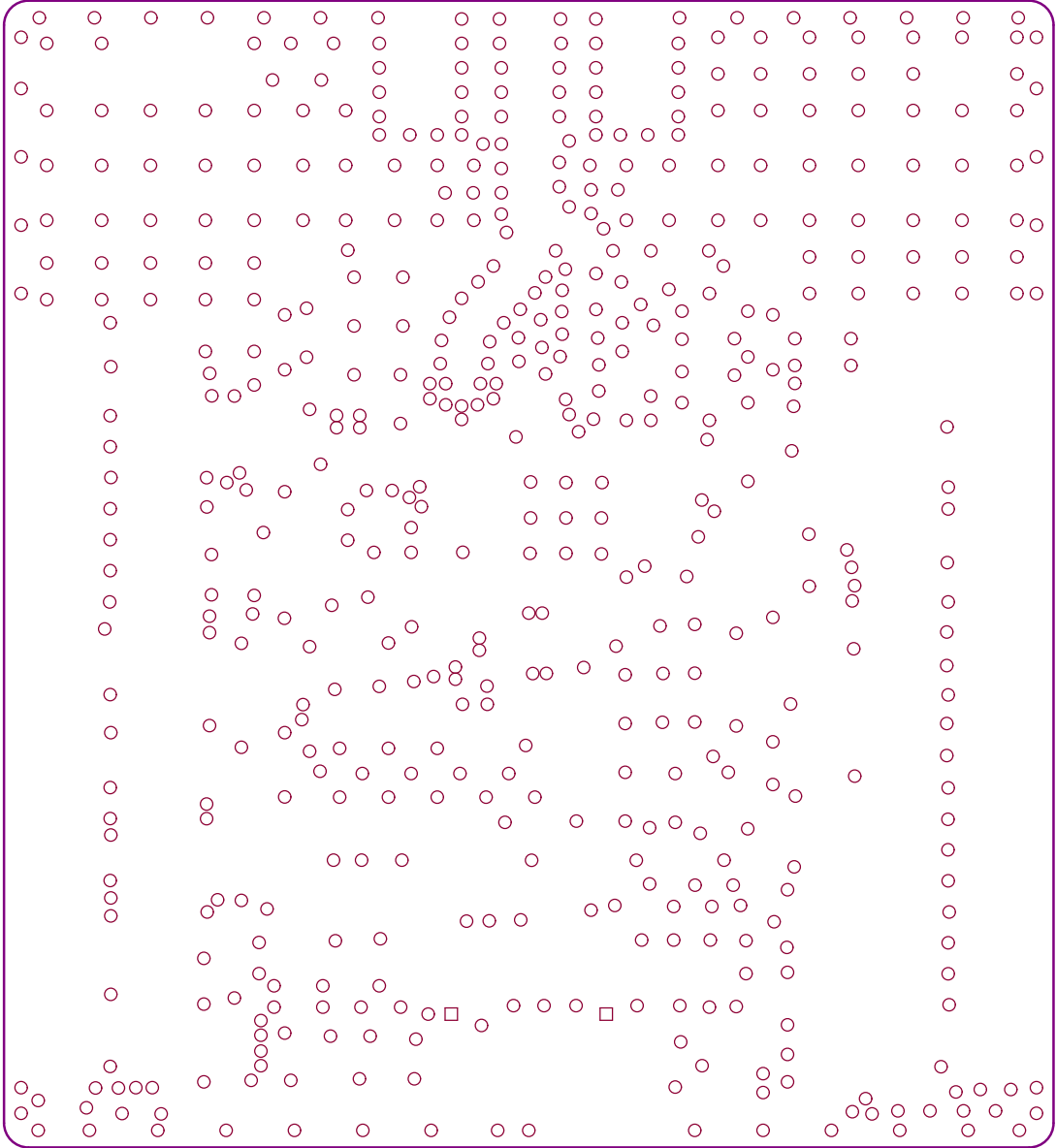
☒ YES

G. THROUGH VIA :

PLUG THE VIAS WHICH ARE COVERED WITH SOLDERMASK ONE OR TWO SIDE.
PLUG MATERIAL : ☒ SOLDERMASK ☐ NON-CONDUCTIVE EPOXY.

H. STACK-UP :

SEE LAYER STACK-UP SEQUENCE FOR OVERALL THICKNESS.



Layer	Name	Material	Thickness	Constant
	Top Overlay			
	Top Solder	Solder Resist	0,015mm	3.5
1	Top Layer	Copper	0,041mm	
	Dielectric 1	Core-028	0,254mm	4.4
2	Signal Layer 1	Copper	0,018mm	
	Dielectric 2	FR4	0,914mm	4.4
3	Signal Layer 2	Copper	0,018mm	
	Dielectric 3	Core-028	0,254mm	4.4
4	Bottom Layer	Copper	0,041mm	
	Bottom Solder	Solder Resist	0,015mm	3.5
	Bottom Overlay			

PCB : TYPE 3

ASPECT-RATIO, AXE Z :
6 :1 à 8 :1
LEVEL "B"

MINIMUM PARAMETERS

DEFAULT
TRACKS : 0.150mm
GAPS : 0.150mm

Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Hole Length
○	542	0.20mm (7.87mil)	PTH	Round	Top Layer - Bottom Layer	Via	-
□	2	1.00mm (39.37mil)	NPTH	Round	Top Layer - Bottom Layer	Pad	-
	544 Total						

Project: MCU_RF_WL3R_QFN32

Layer: Drill Drawing

Gerber: .DRL

Variant: [No Variations]

Ref: MB2339

Date: 2025-MAR-06

Rev: A